

Application No.: 10/811,857

Docket No.: 4459-142

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-2. (cancelled)

3. (currently amended) A semiconductor package comprising:

a first die pad and a plurality of leads arranged about the periphery of the first die pad wherein the first die pad and the leads have a thickness between about 10 mils and about 20 mils;

a first semiconductor device securely attached to an upper surface of the first die pad; the first semiconductor device being electrically coupled to one of the leads; and

a package body formed over the first semiconductor device and the leads in a manner that the lower surfaces of the first die pad and the leads are exposed through the package body; and

~~The semiconductor package as claimed in claim 1, further comprising an output bar wherein the first semiconductor device is electrically coupled to the output bar by at least one heavy gauge aluminum wire.~~

4. (currently amended) A semiconductor package comprising:

a first die pad and a plurality of leads arranged about the periphery of the first die pad wherein the first die pad and the leads have a thickness between about 10 mils and about 20 mils;

a first semiconductor device securely attached to an upper surface of the first die pad; the first semiconductor device being electrically coupled to one of the leads; and

a package body formed over the first semiconductor device and the leads in a manner that the lower surfaces of the first die pad and the leads are exposed through the package body; and

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~~The semiconductor package as claimed in claim 1, further comprising a second die pad having a thickness between about 10 mils and about 20 mils and disposed between the leads, and a second semiconductor device which is securely attached to the second die pad and electrically coupled to the leads and the first semiconductor device by a plurality of gold wires.~~

5. (original) The semiconductor package as claimed in claim 4, wherein the second semiconductor device is a control semiconductor device.

6. (original) The semiconductor package as claimed in claim 4, wherein the second semiconductor device is a control semiconductor device and the control semiconductor device is securely attached to the second die pad by silver epoxy.

7. (cancelled)

8. (currently amended) A semiconductor package comprising:
first and second die pads, and an output bar and a plurality of leads arranged about the periphery of the first and second die pads ~~wherein the first and second die pads;~~
a first semiconductor device securely attached to the first die pad, the first semiconductor device being electrically coupled to the output bar by at least one heavy gauge aluminum wire;
a second semiconductor device securely attached to the second die pad, the second semiconductor device being electrically coupled to the leads and the first semiconductor device;
and
a package body formed over the first semiconductor device, the second semiconductor device, the output bar and the leads in a manner that ~~the lower surfaces of the output bar and the~~ leads are exposed through the package body.

9. (currently amended) The semiconductor package as claimed in claim 8, wherein:

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the first semiconductor device is a power semiconductor device and the power semiconductor device is securely attached to the an upper surface of the first die pad by solder paste, and

the second semiconductor device is a control semiconductor device and the control semiconductor device is securely attached to the second die pad by silver epoxy.

10. (original) The semiconductor package as claimed in claim 8, wherein each lead and the die pads are half-etched to form indentations thereby significantly enhancing the locking of the leads and the die pads in the package body.

11. (original) A semiconductor package comprising: first and second die pads, and a plurality of leads arranged about the periphery of the first and second die pads wherein the die pads and the leads have a thickness between about 10 mils and about 20 mils; a first semiconductor device securely attached to the first die pad; a second semiconductor device securely attached to the second die pad, the second semiconductor device being electrically coupled to the leads and the first semiconductor device; and a package body formed over the first semiconductor device, the second semiconductor device, and the leads in a manner that the lower surfaces of the leads are exposed through the package body.

12. (original) The semiconductor package as claimed in claim 11, wherein: the first semiconductor device is a power semiconductor device and the power semiconductor device is securely attached to the upper surface of the first die pad by solder paste, and the second semiconductor device is a control semiconductor device and the control semiconductor device is securely attached to the second die pad by silver epoxy.

13. (original) The semiconductor package as claimed in claim 11, wherein each lead and the die pads are half-etched to form indentations thereby significantly enhancing the

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locking of the leads and the die pads in the package body.

14-20. (canceled)